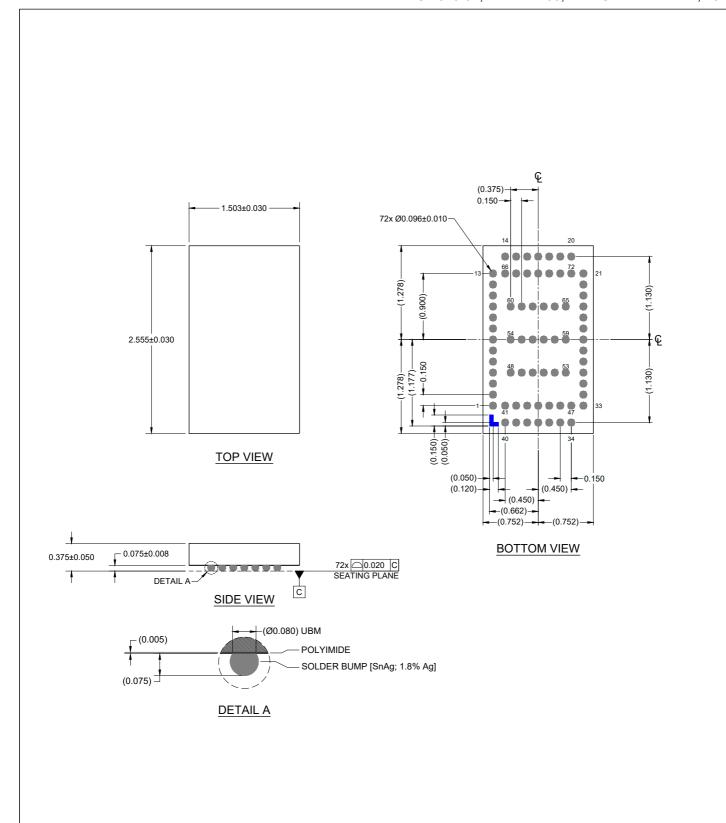
## **Bumped Die Outline Drawing**



Package Code: DICE DICEW 1.503 x 2.555 x 0.375 mm Body, 0.150mm Pitch PSC-4929-01, Revision: 00, Date Created: Feb 11, 2022



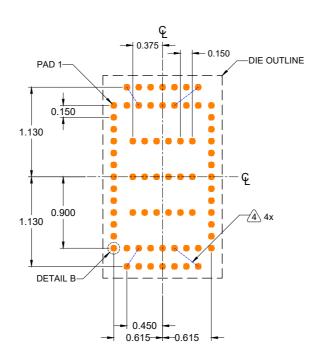
## NOTES:

- 1. All dimensions are in millimeters (mm) and angles are in degrees
- 2. Tolerances of ±0.007mm apply to untoleranced dimensions
- 3. Dimensions in parenthesis ( ) are for reference only

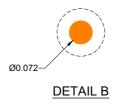




Package Code: DICE DICEW 1.503 x 2.555 x 0.375 mm Body, 0.150mm Pitch PSC-4929-01, Revision: 00, Date Created: Feb 11, 2022



RECOMMENDED LAND PATTERN (Substrate Top View, NSMD Design)





## NOTES:

- 1. All dimensions are in millimeters (mm) and angles are in degrees.
- 2. Land Pattern exhibits substrate pads for die bump connections.
- 3. A complete layout requires additional connections and ground patterns.
- A Substrate circuit requires networks for redundant die bump connections. Land pattern identifies pads to connect, but layout details are not shown.

Page 2 of 2